

6-28-99

06-30-1999



SHEET

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To the Honorable Commissioner of Pat

attached original documents or copy thereof.

1. Name of conveying party(ies):

Cybeq Nano Technologies, Inc.

Additional name(s) of conveying party(ies) attached?

[] Yes [X] No

2. Name and address of receiving party(ies):

Mitsubishi Materials Corporation
Ohtemachi Bldg.
1-6-1 Ohtemachi, Chiyoda-ku
Tokyo, JAPAN 100-0004

Additional name(s) & address(es) attached?
[] Yes [X] No

3. Nature of Conveyance:

[X] Assignment [] Merger
[] Security Agreement [] Change of Name
[] Other

Execution Date: 24 June 1999

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s)

09/261,112 filed 3 March 1999
09/294,547 filed 19 April 1999

B. Patent No.(s)

5,205,082 issued 27 April 1993
4,918,870 issued 24 April 1990
5,527,209 issued 18 June 1996
5,443,416 issued 22 August 1995

Additional numbers attached? [] Yes [X] No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: R. Michael Ananian
Internal Address: FLEHR HOHBACH TEST
ALBRITTON & HERBERT LLP

Street Address: SUITE 3400
FOUR EMBARCADERO CENTER
City: SAN FRANCISCO
State: CA Zip: 94111-4187

6. Total number of applications and patents involved:

6

7. Total fee (37 CFR 3.41):.....\$ _____

[] Enclosed
[X] Authorized to be charged to deposit account

8. Deposit account number: 06-1300
Please debit any underpayment or credit any overpayment to the above deposit account.

Our Order No. A-65012/RMA
(Attach duplicate of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and a attached copy is a true copy of the original document.

R. Michael Ananian
Name of Person Signing

R. Michael Ananian
Signature

June 25, 1999
Date

Total number of pages including cover sheet, attachments and document: 4

OMB No. 0651-0011 (exp. 4/94)

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Commissioner of Patents and Trademarks, Box Assignments
Washington, DC 20231

File No. G-65012/RMA

Rev. 8/9 (39811)

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ASSIGNMENT

FROM CYBEQ NANO TECHNOLOGIES, INC.
TO
MITSUBISHI MATERIALS CORPORATION

WHEREAS, CYBEQ NANO TECHNOLOGIES, INC. (CNT), a wholly-owned subsidiary of Mitsubishi Materials Corporation (MMTL), a Japanese corporation, (hereinafter "Assignor") is holder and owner of a certain right, title and interest (either a remaining sixty-seven percent interest or the entire one-hundred percent interest as indicated in Schedule A) in and to certain United States Letters Patents and applications for Letters Patents, all of which are identified on Schedule A attached hereto, together with the inventions disclosed therein and to any corresponding international and/or foreign applications; and

WHEREAS, MITSUBISHI MATERIALS CORPORATION (MMTL), a Japanese corporation, (hereinafter "Assignee") is desirous of acquiring Assignor's right, title and interest in and to the aforesaid Letters Patents and applications for Letters Patent and any corresponding foreign and international Letters Patents and applications for Letters Patent, together with the inventions disclosed therein, and any and all causes of action and rights of recovery for past infringement of said Letters Patents, and all of the rights vested in said Assignor by virtue of any and all instruments of assignment concerning the aforesaid Letters Patents and applications for Letters Patent in Schedule A, and any corresponding foreign and/or international Letters Patents and applications for Letters Patent, and/or by virtue of other instruments pursuant to which Assignor became vested with said ownership, including Assignor's right, title and interest in and to any and all improvements acquired pursuant to the terms of said instruments of assignment.

NOW THEREFORE, in consideration of the sum of One United States Dollar (\$1.00) and for other good and valuable consideration received by Assignor from Assignee, the receipt in full of which is hereby acknowledged:

1. Assignor hereby sells, assigns, transfers and conveys unto Assignee Assignor's entire right, title and interest in and to said Letters Patents, United States applications for Letters Patent and Letters Patents to be granted thereon, together with the inventions disclosed in said applications, and all Letters Patents of the United States and international patents and patents of foreign countries which may be granted thereon, including each and every Letters Patent granted on any application which is a division, substitution or continuation of the Letters Patent and applications therefor specifically identified in Schedule A and in and to each and every reissue and extension of said Letters Patent.

2. Assignor further sells, assigns, transfers and quitclaims unto Assignee all of Assignor's rights and interest, past and future, acquired by Assignor pursuant to the terms and provisions of assignments from the inventors, whether acquired directly or indirectly through an intervening assignment in the chain of title, and/or by virtue of other instruments pursuant to which Assignor became vested with said ownership, including the right, title and interest in and to any and all improvements acquired pursuant to the terms of said instruments of assignment.

3. Assignor further sells, assigns, transfers and conveys unto said Assignee Assignor's right, title and interest in and to any and all causes of action and rights of recovery for past infringement of the Letters Patents herein assigned in the United States and internationally according to the rights conveyed by the Letters Patents and applications for Letters Patent.


4. Assignor hereby covenants and agrees to cooperate with Assignee whereby the latter may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include

prompt execution of all papers prepared at the expense of Assignee which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed.

5. The terms, covenants and provisions of this assignment shall inure to the benefit of Assignee, its successors, assigns and/or other legal representatives, and shall be binding upon Assignor, its successors, assigns and/or other legal representatives.

IN WITNESS WHEREOF, Assignor has executed and delivered this assignment instrument this 24th day of June, 1999, at Palo Alto, California, USA.

CYBEQ NANO TECHNOLOGIES, INC.

By 
Yoshio Nishino, Cybeq Nano Technologies, Inc.

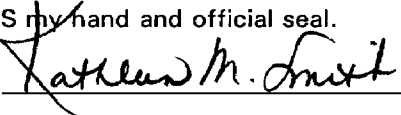
IN WITNESS WHEREOF, Assignee agrees to and accepts this assignment instrument this 24th day of June, 1999 at Palo Alto, California, USA.

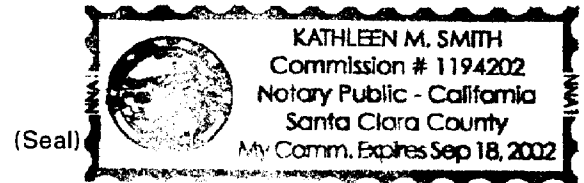
MITSUBISHI MATERIALS CORPORATION

By 
Masayuki Ito, Mitsubishi Materials Corporation

State of California)
:
County of Santa Clara)

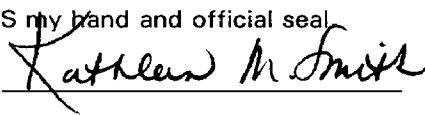
On 24 June 1999, before me, Kathleen M. Smith, Notary Public of the State of California, personally appeared Yoshio Nishino, ~~personally known to me~~ (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument and acknowledged to me that he executed the same in his authorized capacity, and that by his signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

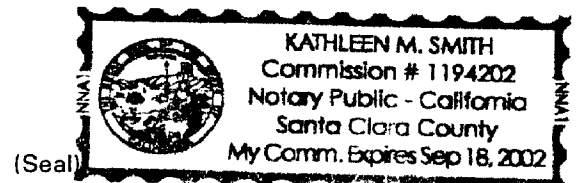
WITNESS my hand and official seal.
Signature 



State of California)
:
County of Santa Clara)

On 24 June 1999, before me, Kathleen M. Smith, Notary Public of the State of California, personally appeared Masayuki Ito, ~~personally known to me~~ (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument and acknowledged to me that he executed the same in his authorized capacity, and that by his signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.
Signature 



SCHEDULE A

UNITED STATES PATENTS AND PATENT APPLICATIONS

<i>Serial No. Filing Date</i>	<i>Patent No. Issue Date</i>	<i>Title</i>	<i>Current Interest Assigned From CNT to MMTL</i>	<i>Inventor Names</i>
07/811,568 12/20/91	5,205,082 4/27/93	Wafer Polisher Head Having Floating Retainer Ring	67% to MMTL (33% already assigned to MMTL)	Norm Shendon Kenneth C. Struven Robert J. Kolenkow
06/864,282 5/16/86	4,918,870 4/24/90	Floating Subcarriers For Wafer Polishing Apparatus	67% to MMTL (33% already assigned to MMTL)	Walter Torbert Kenneth C. Struven Robert E. Lorenzini Anthony C. Bonora
08/449,556 5/24/95	5,527,209 6/18/96	Wafer Polisher Head Adapted For Easy Removal of Wafers	67% to MMTL (33% already assigned to MMTL)	Konstantine Volodarsky Jiro Kajiwara Herbert W. Owens Jr. Jan H. King
08/119,972 9/9/93	5,443,416 8/22/95	Rotary Union For Coupling Fluids In A Wafer Polishing Apparatus	67% to MMTL (33% already assigned to MMTL)	Konstantine Volodarsky Jiro Kajiwara Herbert W. Owens Jr. Jan H. King
09/261,112 3/3/99	Pending	Chemical Mechanical Polishing Head Assembly Having Floating Wafer Carrier and Retaining Ring	100% to MMTL	Gerard S. Maloney Scott Chin John J. Geraghty William Dyson, Jr. Tanlin Dickey
09/294,547 4/19/99	Pending	Chemical Mechanical Polishing Head Assembly Having Floating Wafer Retaining Ring and Wafer Carrier With Multi-Zone Polishing Pressure Control	100% to MMTL	Huey-Ming Wang Gerard S. Maloney Scott Chin John J. Geraghty William Dyson, Jr. Tanlin Dickey

MMTL: Mitsubishi Materials Corporation

CNT: Cybeq Nano Technologies